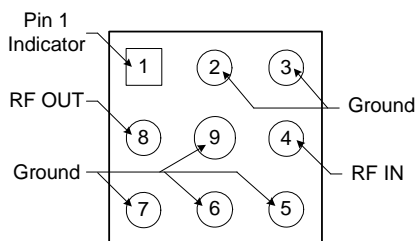




Features

- Reliable, Low-Cost HBT Design
- 12.0dB Gain, +13.7 dBm P1dB at 2GHz
- High P1dB of +14.0dBm at 6.0GHz and +11.0dBm at 14.0GHz
- Single Power Supply Operation
- 50Ω I/O Matched for High Freq. Use



Applications

- Narrow and Broadband Commercial and Military Radio Designs
- Linear and Saturated Amplifiers
- Gain Stage or Driver Amplifiers for MWRadio/Optical Designs (PTP/PMP/LMDS/UNII/VSAT/WiFi/Cellular/DWDM)

Functional Block Diagram

Product Description

The NBB-302 cascadable broadband InGaP/GaAs MMIC amplifier is a low-cost, high-performance solution for general purpose RF and microwave amplification needs. This 50Ω gain block is based on a reliable HBT proprietary MMIC design, providing unsurpassed performance for small-signal applications. Designed with an external bias resistor, the NBB-302 provides flexibility and stability. The NBB-302 is packaged in a low-cost, surface-mount ceramic package, providing ease of assembly for high-volume tape-and-reel requirements. It is available in either packaged or chip (NBB-300-D) form, where its gold metallization is ideal for hybrid circuit designs.

Ordering Information

| | |
|-------------|--|
| NBB-302 | 25 piece bag |
| NBB-302-SB | 5 piece sample bag |
| NBB-302-SR | 100 pieces on 7" reel |
| NBB-302-T1 | 1000 pieces on 13" reel |
| NBB-302-PCK | Populated evaluation board with 5 piece sample bag |
| NBB-X-K1 | Extended Frequency InGaP Amp Designer's Tool Kit |

Optimum Technology Matching® Applied

- | | | | |
|---|--------------------------------------|-------------------------------------|------------------------------------|
| <input type="checkbox"/> GaAs HBT | <input type="checkbox"/> SiGe BiCMOS | <input type="checkbox"/> GaAs pHEMT | <input type="checkbox"/> GaN HEMT |
| <input type="checkbox"/> GaAs MESFET | <input type="checkbox"/> Si BiCMOS | <input type="checkbox"/> Si CMOS | <input type="checkbox"/> BiFET HBT |
| <input checked="" type="checkbox"/> InGaP HBT | <input type="checkbox"/> SiGe HBT | <input type="checkbox"/> Si BJT | <input type="checkbox"/> LDMOS |

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Absolute Maximum Ratings

| Parameter | Rating | Unit |
|-----------------------|-------------|------|
| RF Input Power | +20 | dBm |
| Power Dissipation | 300 | mW |
| Device Current | 70 | mA |
| Channel Temperature | 150 | °C |
| Operating Temperature | -45 to +85 | °C |
| Storage Temperature | -65 to +150 | °C |

Exceeding any one or a combination of these limits may cause permanent damage.



Caution! ESD sensitive device.

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability. Specified typical performance or functional operation of the device under Absolute Maximum Rating conditions is not implied.

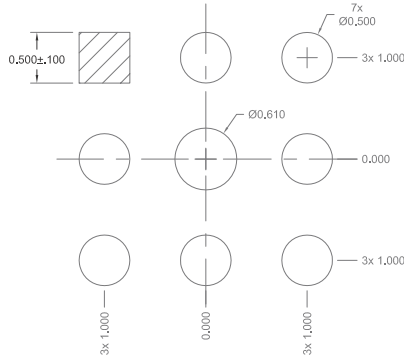
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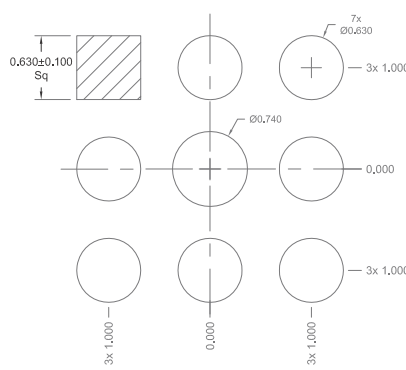
RFMD Green: RoHS compliant per EU Directive 2002/95/EC, halogen free per IEC 61249-2-21, < 1000ppm each of antimony trioxide in polymeric materials and red phosphorus as a flame retardant, and <2% antimony in solder.

| Parameter | Specification | | | Unit | Condition |
|---|---------------|------------|------|-------|---|
| | Min. | Typ. | Max. | | |
| Overall | | | | | $V_D = +3.9V, I_{CC} = 50mA, Z_0 = 50\Omega, T_A = +25^\circ C$ |
| Small Signal Power Gain, S ₂₁ | 12.0 | 13.5 | | dB | f=0.1GHz to 1.0GHz |
| | 11.0 | 13.0 | | dB | f=1.0GHz to 4.0GHz |
| | | 12.5 | | dB | f=4.0GHz to 6.0GHz |
| | 9.0 | 10.5 | | dB | f=6.0GHz to 12.0GHz |
| | | 9.5 (avg.) | | dB | f=12.0GHz to 14.0GHz |
| Gain Flatness, GF | | ±0.6 | | dB | f=0.1GHz to 8.0GHz |
| Input and Output VSWR | | 2.4:1 | | | f=0.1GHz to 4.0GHz |
| | | 2.0:1 | | | f=4.0GHz to 12.0GHz |
| | | 2.8:1 | | | f=12.0GHz to 15.0GHz |
| Bandwidth, BW | | 12.5 | | GHz | BW3 (3dB) |
| Output Power at -1dB Compression, P _{1dB} | | 13.7 | | dBm | f=2.0GHz |
| | | 14.8 | | dBm | f=6.0GHz |
| | | 11.0 | | dBm | f=14.0GHz |
| Noise Figure, NF | | 5.5 | | dB | f=3.0GHz |
| Third Order Intercept, IP ₃ | | +23.5 | | dBm | f=2.0GHz |
| Reverse Isolation, S ₁₂ | | -15 | | dB | f=0.1GHz to 12.0GHz |
| Device Voltage, V _D | 3.6 | 3.9 | 4.2 | V | |
| Gain Temperature Coefficient, $\delta G_T / \delta T$ | | -0.0015 | | dB/°C | |
| MTTF versus Temperature at I_{CC}=50mA | | | | | |
| Case Temperature | | 85 | | °C | |
| Junction Temperature | | 122.9 | | °C | |
| MTTF | | >1,000,000 | | hours | |
| Thermal Resistance | | | | | |
| θ_{JC} | | 194 | | °C/W | $\frac{J_T - T_{CASE}}{V_D \cdot I_{CC}} = \theta_{JC} (^\circ C / Watt)$ |

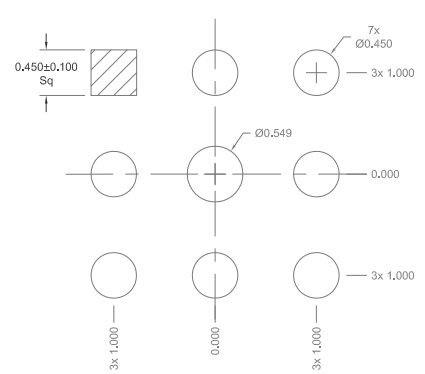
Recommended PCB Layout



PCB METAL PATTERN



PCB SOLDER MASK PATTERN



PCB STENCIL PATTERN